

CND0208A

Infrared Optocal Module (IrDA)

Infrared data link for cellular phones, peripheral devices

■ Features

- Compliant with IrDA Ver.1.2
- Reception distance: 50 cm
- Corresponding reflow solder (260°C)
- Ultra-small top view package (2.0 mm × 7.2 mm × 1.7 mm)

■ Type

- GaAlAs LED + IC + PIN Photodiode

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Operating supply voltage	V_{CC}	-0.5 to +3.8	V
Output voltage	V_O	-0.5 to +3.8	V
Input voltage	V_I	-0.5 to +3.8	V
Shutdown input voltage	V_{SD}	-0.5 to +3.8	V
LED operating supply voltage	V_{LEDA}	-0.5 to +7.0	V
Pulse forward current *	I_{FP}	300	mA
Low level output current	I_{OL}	10	mA
Operating ambient temperature	T_{opr}	-20 to +70	°C
Storage temperature	T_{stg}	-30 to +85	°C

Note) *: $t_w \leq 90 \mu\text{s}$, Duty $\leq 25\%$

■ Operatong Condition

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Operating supply voltage	V_{CC}		2.4	2.8	3.3	V
LED operating supply voltage	V_{LEDA}		2.6		4.2	V

■ Electrical-Optical Characteristics $V_{CC} = 2.8 \text{ V}$, $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
High level supply current *1	I_{CCH}	$V_{TXD} = 0.5 \text{ V}$, $V_{SD} \leq 0.5 \text{ V}$		90	120	μA
Low level supply current *1	I_{CCL}	$V_{TXD} = 0.5 \text{ V}$, $V_{SD} \leq 0.5 \text{ V}$		150	360	μA
Shut down supply current *1	I_{CCSD}	$V_{CC} \geq V_{SD} \geq V_{CC} - 0.3$ (SD = High) $V_{TXD} = 0.5 \text{ V}$		10	200	nA
Maximum reception distance *4	L_{max}	$V_{LEDA} = V_{CC} = 2.6 \text{ V}$, $V_{SD} \leq 0.5 \text{ V}$, External components	50			cm
Data Rates	—		9.6		115.2	kbps

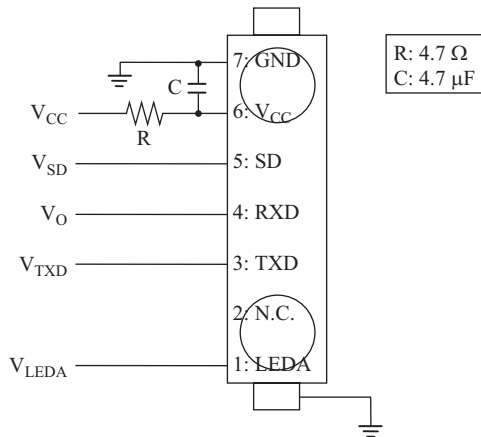
■ Electrical-Optical Characteristics (Continued) $V_{CC} = 2.8\text{ V}$, $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Transmitter						
Peak emission wavelength *1	λ_p	$V_{SD} \leq 0.5\text{ V}$, $V_{LEDA} = 3.2\text{ V}$ Duty 3/16	878	883	888	nm
		$V_{SD} \leq 0.5\text{ V}$, $V_{LEDA} = 3.2\text{ V}$ Duty 3/16 $T_a = -20^\circ\text{C}$ to $+70^\circ\text{C}$	850	883	900	nm
Pulse forward current *1	I_{FP}	$V_{LEDA} = V_{CC} = 3.1\text{ V}$, $V_{SD} \leq 0.5\text{ V}$ TXD Duty 3/16	100	135	150	mA
Center radiant intensity *1, 2, 9	$\theta_T = 0$	$V_{LEDA} = V_{CC} = 2.6\text{ V}$, $V_{SD} \leq 0.5\text{ V}$ TXD Duty 3/16	20	35		mW/sr
	$\theta_T = \pm 15$	$V_{LEDA} = V_{CC} = 2.6\text{ V}$, $V_{SD} \leq 0.5\text{ V}$ TXD Duty 3/16	14.5			mW/sr
High level input voltage *1	V_{IH}	$V_{LEDA} = 3.2\text{ V}$	$V_{CC} - 0.3$		V_{CC}	V
Low level input voltage *1	V_{IL}	$V_{LEDA} = 3.2\text{ V}$	0		0.5	V
TX half-angle	θ_T		± 15			°
Rise time *1, 3	t_r	$V_{LEDA} = 3.2\text{ V}$, $t_w = 1.6\text{ }\mu\text{s}$, $R_L = 50\text{ }\Omega$		0.3	0.6	μs
Fall time *1, 3	t_f	$V_{LEDA} = 3.2\text{ V}$, $t_w = 1.6\text{ }\mu\text{s}$, $R_L = 50\text{ }\Omega$		0.3	0.6	μs
TX wake up time *7	t_{Twu}			0.3	1	μs
Intensity delay time *1, 3	I_{DT}	$V_{LEDA} = 3.2\text{ V}$			200	ns
Maximum pulse width	$T_{wLEDmax}$	TXD = Low \rightarrow High	20	50	100	μs
Overshoot	O_S				25	%
Edge jitter	E_J		-40		40	ns
Receiver						
Minimum input irradiance	E_{Imin}	$V_{LEDA} = V_{CC} = 2.6\text{ V}$, $V_{SD} \leq 0.5\text{ V}$			5.8	$\mu\text{W}/\text{cm}^2$
Maximum input irradiance	E_{Imax}	$V_{SD} \leq 0.5\text{ V}$	500			mW/cm^2
High level output voltage *5	V_{OH}	Non signal condition $I_{OH} = -200\text{ }\mu\text{A}$, $V_{SD} \leq 0.5\text{ V}$	$V_{CC} - 0.3$		V_{CC}	V
Low level output voltage *6	V_{OL}	$I_{OL} = 500\text{ }\mu\text{A}$, $V_{SD} \leq 0.5\text{ V}$	0		0.5	V
RX half angle	θ_R		± 15			°
RXD output pulse width	T_{WR}	$C_L = 15\text{ pF}$, 9.6 kbps to 115.2 kbps	1.0	2.3	4.2	μs
RX wake up time *8	t_{Rwu}	$E_I = 8.1\text{ }\mu\text{W}/\text{cm}^2$		200	400	μs
Receiver latency time	t_L	$E_I = 8.1\text{ }\mu\text{W}/\text{cm}^2$		100	200	μs
Rise time	t_r	$C_L = 15\text{ pF}$			300	ns
Fall time	t_f	$C_L = 15\text{ pF}$			300	ns

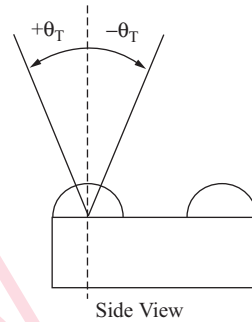
■ Electrical-Optical Characteristics (Continued)

Note) Measuring circuit

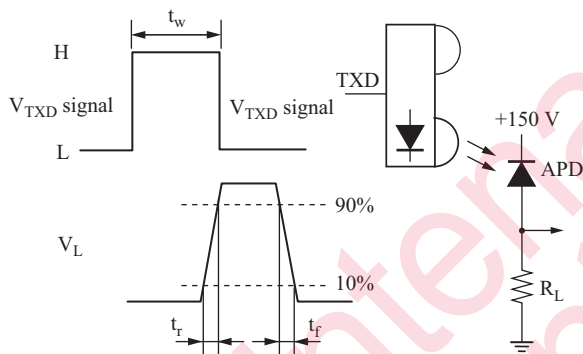
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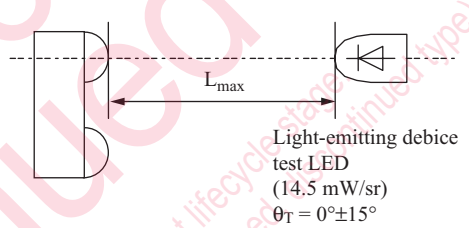
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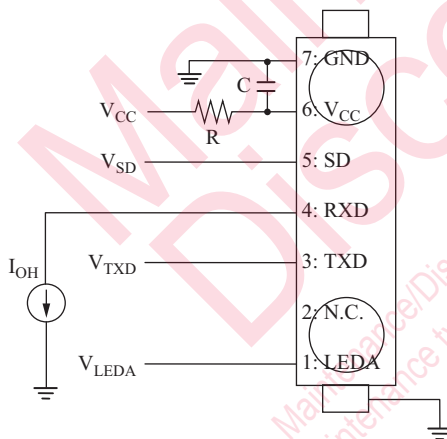
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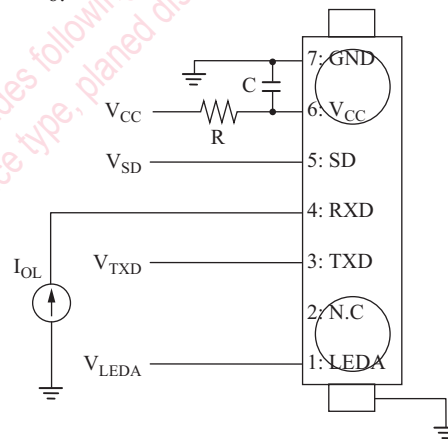
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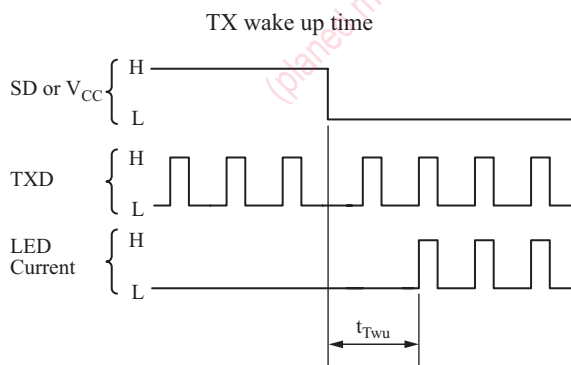
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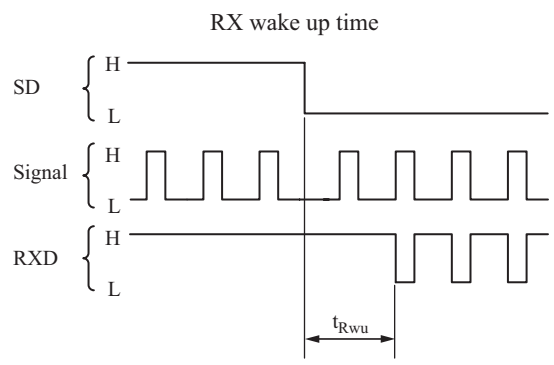
*6:



*7:



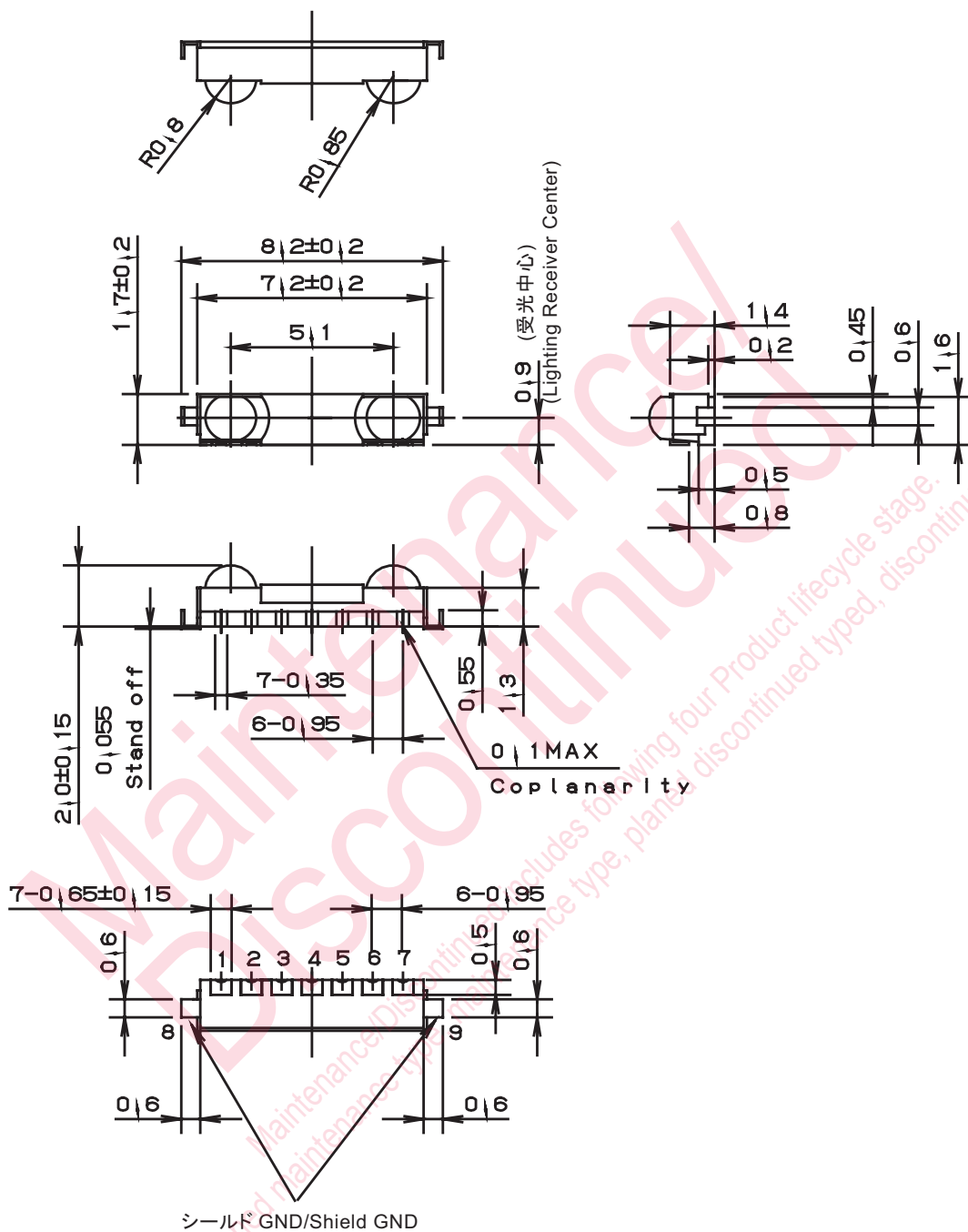
*8:



*9: Eye-Safety IEC60825-1 Class1 Eye safe

■ Package (Unit: mm)

KMTLTM7K0001



• Pin name

- | | |
|---------|--------------------|
| 1. LEDA | 6. V _{CC} |
| 2. N.C. | 7. GND |
| 3. TXD | 8. Shield GND |
| 4. RXD | 9. Shield GND |
| 5. SD | |

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